Substrate Ball Pad Metallization Change for Virtex-6 FPGA Flip Chip Packages

Overview

The purpose of this notification is to communicate that Xilinx has qualified an additional substrate ball pad metallization called CuSOP for Virtex®-6 FPGA flip chip packages.

Description

Xilinx has qualified an additional substrate ball pad metallization called CuSOP for Virtex®-6 FPGA flip chip packages. The implementation of CuSOP is an industry trend with our substrate and assembly suppliers. This enables Xilinx to better support long-term customer demand. Xilinx will begin cross shipping Virtex-6 FPGA products with this change upon the release of this PCN-FYI.

Xilinx will revise the corresponding MDDS and application note "XAPP427" for Virtex-6 FPGA flip chip packages. CuSOP is already qualified and in production for all 7 Series FPGA products. There is no change in the fit, form or function with this change. There is no change to the package substrate and solder balls.

Products Affected

This change affects all speed, package, and temperature variations of the commercial (C), extended (E) and industrial (I) grade Virtex-6 FPGA devices. Affected device and package combinations are included in Table 1, below.

Table 1: Product Changes

Xilinx Product	Package	Xilinx Product	Package
XC6VLX75T	FF(G)484	XC6VSX475T	FF(G)1156
XC6VLX75T	FF(G)784	XC6VSX475T	FF(G)1759
XC6VLX130T	FF(G)484	XC6VHX250T	FF(G)1154
XC6VLX130T	FF(G)784	XC6VHX255T	FF(G)1155
XC6VLX130T	FF(G)1156	XC6VHX255T	FF(G)1923
XC6VLX195T	FF(G)784	XC6VHX380T	FF(G)1154
XC6VLX195T	FF(G)1156	XC6VHX380T	FF(G)1155
XC6VLX240T	FF(G)784	XC6VHX380T	FF(G)1923
XC6VLX240T	FF(G)1156	XC6VHX380T	FF(G)1924
XC6VLX240T	FF(G)1759	XC6VHX565T	FF(G)1923
XC6VLX365T	FF(G)1156	XC6VHX565T	FF(G)1924
XC6VLX365T	FF(G)1759	XC6VCX75T	FF(G)484
XC6VLX550T	FF(G)1759	XC6VCX75T	FF(G)784
XC6VLX550T	FF(G)1760	XC6VCX130T	FF(G)484
XC6VLX760	FF(G)1760	XC6VCX130T	FF(G)784
XC6VSX315T	FF(G)1156	XC6VCX130T	FF(G)1156
XC6VSX315T	FF(G)1759	XC6VCX195T	FF(G)784

Table 1 (Continued): **Product Changes**

Xilinx Product	Package
XC6VCX195T	FF(G)1156
XC6VCX240T	FF(G)784

Xilinx Product	Package
XC6VCX240T	FF(G)1156

Key Dates and Ordering Information

Xilinx will begin to cross-ship Virtex-6 FPGA production parts with this change upon release of this PCN-FYI.

Qualification Data

Xilinx has completed and successfully passed all the necessary qualification. Reliability data for all Virtex-6 FPGA products will be available in UG116, Product Reliability Monitor.

Response

No response is required. For additional information or questions, please contact Xilinx Technical Support.

Important Notice: Xilinx Customer Notifications (XCNs, XDNs, and Quality Alerts) can be delivered via e-mail alerts sent by the Support website (http://www.xilinx.com/support). Register today and personalize your "Documentation and Design Advisory Alerts" area to include Customer Notifications. Xilinx Support provides many benefits, including the ability to receive alerts for new and updated information about specific products, as well as alerts for other publications such as data sheets, errata, application notes, etc. For information on how to sign up, refer to Answer Record 18683: http://www.xilinx.com/support/answers/18683.htm.

Revision History

The following table shows the revision history for this document:

Date	Version	Description of Revisions
07/16/12	1.0	Initial release.

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